# XN04604 (XN4604)

## Silicon NPN epitaxial planar type (Tr1) Silicon PNP epitaxial planar type (Tr2)

For amplification of low-frequency output

#### ■ Features

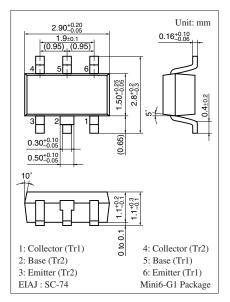
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

#### ■ Basic Part Number

• 2SD1328 + 2SB0970 (2SB970)

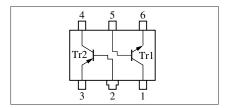
## ■ Absolute Maximum Ratings T<sub>a</sub> = 25°C

Parameter		Symbol	Rating	Unit	
Tr1	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	25	V	
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	12	V	
	Collector current	$I_C$	0.5	A	
	Peak collector current	$I_{CP}$	1	A	
Tr2	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-15	V	
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-10	V	
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-7	V	
	Collector current	$I_C$	- 0.5	A	
	Peak collector current	$I_{CP}$	-1	A	
Overall	Total power dissipation	$P_{T}$	300	mW	
	Junction temperature	$T_{j}$	150	°C	
	Storage temperature	$T_{stg}$	-55 to +150	°C	



Marking Symbol: 51

#### Internal Connection



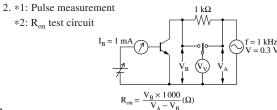
Note) The part number in the parenthesis shows conventional part number.

# $\blacksquare$ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

### • Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \ \mu A, I_E = 0$	25			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, I_C = 0$	12			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 25 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$	200		800	_
	h <sub>FE2</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}$	60			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 0.5 \text{ A}, I_B = 20 \text{ mA}$		0.13	0.40	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 0.5 \text{ A}, I_B = 20 \text{ mA}$			1.2	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		10		pF
(Common base, input open circuited)						
ON resistance *2	Ron			1.0		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



### • Tr2

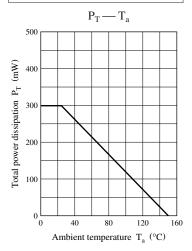
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = -10 \ \mu A, I_E = 0$	-15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1  \text{mA},  I_{\rm B} = 0$	-10			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \ \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -10 \text{ V}, I_E = 0$			- 0.1	μΑ
Forward current transfer ratio *	h <sub>FE1</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$	100		350	_
	h <sub>FE2</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -1 \text{ A}$	60			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -0.4 \text{ A}, I_B = -8 \text{ mA}$		- 0.16	- 0.30	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -0.4 \text{ A}, I_B = -8 \text{ mA}$		- 0.8	-1.2	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		130		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		22		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

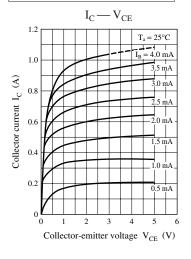
2. \*: Pulse measurement

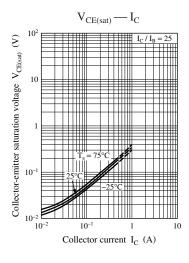
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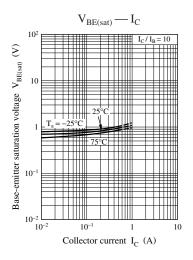
#### Common characteristics chart

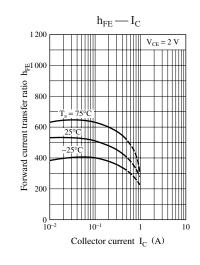


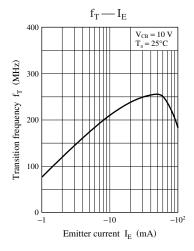
### Characteristics charts of Tr1

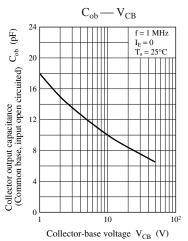








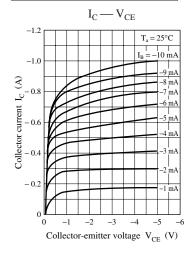


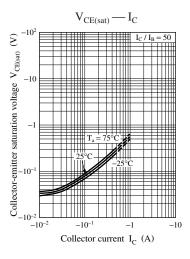


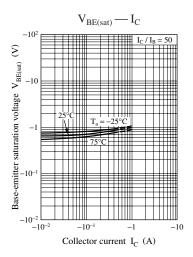
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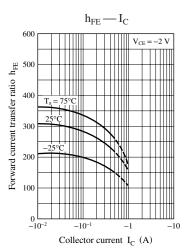
# **Panasonic**

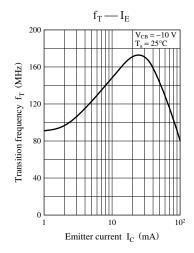
### Characteristics charts of Tr2

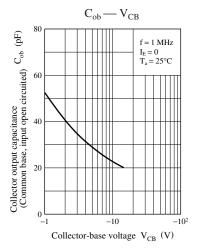












4 SJJ00084BED

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